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	D-110 4	RECOMMENDATION FOR SOLDER PROCESSING
harring har-flex THR straight female con	nnector RoHS Compliant	
Ů	-	Solder paste recommendation
GENERAL INFORMATION	· · · · · · · · · · · · · · · · · · ·	The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb4
		PCB pad plating
No. of contacts	from 6 to 100poles, all even numbers	The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn.
Contact spacing	1,27mm x 1,27mm [0,050"x0,050"]	Stencil recommendation
Test Voltage	500V	The solder deposition has to be placed on the pad area of the contact solder tines.
Contact resistance	< 25 mOhm	Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads.
Insulation resistance	≥ 10x10^9Ω	The size of the solder stencil apertures is depending on the thickness of the stencil.
Working current acc. to IEC 60512, at 70°C, 80% derating	see derating diagram	In general, a thinner stencils will need larger apertures to result in the required volume of solder paste. The minimum required solder paste volume for the signal pins is 0,094mm³, for the hold down it is 1,179mm³.
Working temperature range	-55°C +125°C	For example, this can be achieved with the following stencil data:
Termination technology	SMT	Signal pins
Reflow processing temperature (acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 150s > 217°C min. 30s > 240°C	Stencil thickness PCB pad size proposal stencil aperture size calculated solder paste volume
,		150 µm 1,1 x 0,8 mm 0,99 x 0,72 mm 0,107 mm³
Clearance & creepage distance	0,4mm min.	Hold-downs
Insertion force (depending on mating connector) Withdrawal force (depending on mating connector)	approximately 0,5N/contact approximately 0,5N/contact	
, , , , , , , , , , , , , , , , , , , ,	PL1 : 500 mating cycles	Stencil thickness PCB pad size proposal stencil aperture size calculated solder paste volume
Mating cycles	PL2 : 250 mating cycles	150 μm Ø0,8 mm Ø2,3 mm 1,179 mm³
RoHS - compliant	Yes	If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging
Leadfree	Yes	stencil aperture. Depending on the PCB design, the solder deposition may protrude the PCB pads. But to achieve a
Working voltage acc. to to IEC 60664-1	100V / 150V (depending on installation category)	sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.
UL file acc. UL 1977	ECBT2.E102079	
UL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079	Coplanarity of contacts
PSL level acc. ECA/IPC/JEDEC J-STD-075	PSL R0	All connectors are tested for coplanarity of contacts and are in the range of 6 pin to 50 pin: ≤ 0,1mm
MSL level acc. ECA/IPC/JEDEC J-STD-020D	MSL 1	52 pin to 68 pin: ≤ 0,12mm
	1 1 1	70 pin to 80 pin: ≤ 0,13mm
INSULATOR MATERIAL		82 pin to 100 pin: ≤ 0,15mm
Material	LCP (liquid crystalline polymer)	Performance level
Color	Black	Performance level 1 (recommended for majority of applications): 500 mating cycles with the following procedure.
UL classification	UL94-V0	Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 pp Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance
Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)	and visual inspection.
CONTACT MATERIAL		Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.
		Part number definition : 15 2
Contact material	Copper alloy	Performance level 2: 250 mating cycles with the following procedure.
Plating termination zone	Sn	Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb
Plating contact sliding side	Au over PdNi (acc. to Performance level)	Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance
DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacit	y)	and visual inspection. Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.
		Part number definition: 15 6
The current carrying capacity is limited by maximum	A Hearther Spoil - 1800poil	
temperature of materials for inserts and contacts including		Performance level S4: 500 mating cycles. Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm PdNi
terminals.	₹ 3	Part number definition: 15 5
The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when	pe	August Cale Ferragina tal
simultaneous power on all contacts is given, without	2 2 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	Original Size DIN A3 1:1 Sub.
exceeding the maximum temperature.	i lectr	All rights recoved Created by Inspected by Standardisation Date State
Control and test presedures asserting to DIN IEC 20540 5	ш	Att rights reserved ZHUANGJ LUOK ROEBEN 2021 12 16 Final Paleage
	0 10 10 10 10 10 10 10 10 10 10 10 10 10	Title Doc-Key / ELT
Control and test procedures according to DIN IEC 60512-5		har-flex THR straight female
derating curve at Imax*0,8 (IEC 60512-5-2)	0 10 20 30 40 30 60 70 60 30 100 110 120 130	HARTING [500000196789
·	Temperature [°C]	HARTING
·	Temperature [°C]	HARTING

